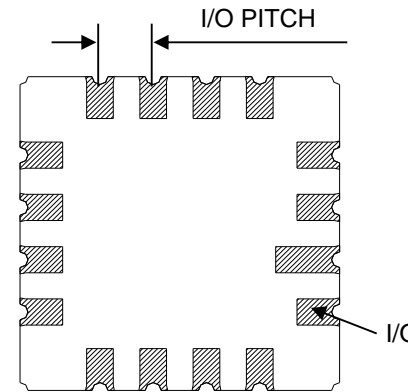
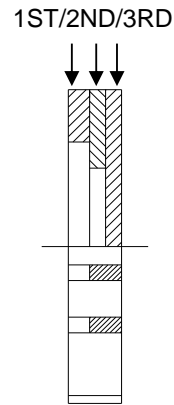
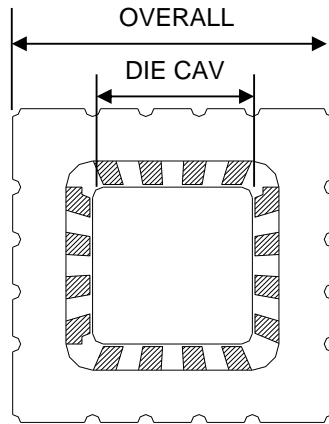
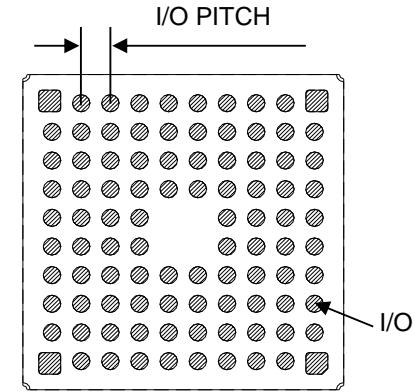


## KYOCERA IMAGE SENSOR PACKAGE

Inquiries about this list ?  
Please click here.



Leadless Chip Carrier (LCC)  
= Quad Flat No Lead (QFN)



Land Grid Array® Package  
Land Grid Array is a registered trade mark  
of KYOCERA Corporation in Japan.

#=Connected pad number  
N=No Metallization  
0=No Connection

UNIT : mm

R0189F

I/O COUNT	DIE CAV	OVERALL	LAYER THICKNESS				I/O PITCH	PACKAGE TYPE	KYOCERA ALUMINA CODE	CONNECTION		DRAWING No.	TOOL
			1ST	2ND	3RD	TOTAL				SEAL RING	DIE ATTACH		
16	3.00 SQ.	6.00 SQ.	0.40	0.30	0.30	1.00	1.00	LCC	A440	N	6	KD-DB1N95	HARD
16	3.00 SQ.	6.00 SQ.	0.40	0.30	0.30	1.00	1.00	LCC	A440	N	6	KD-DB6M86 (Array Panel)	HARD
28	4.00 SQ.	6.50 SQ.	0.40	0.40	0.20	1.00	0.70	LCC	A440	N	N	KD-DA6L83	HARD
28	4.00 SQ.	6.50 SQ.	0.40	0.40	0.20	1.00	0.70	LCC	A440	26	N	KD-DB5676	HARD
28	4.20 SQ.	6.50 SQ.	0.40	0.40	0.20	1.00	0.70	LCC	A440	N	N	KD-DB0G18	SOFT
32	5.50 SQ.	8.00 SQ.	0.40	0.40	0.20	1.00	0.70	LCC	A440	N	N	KD-DA6L81	SOFT

#=Connected pad number  
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R0189F

UNIT : mm

I/O COUNT	DIE CAV	OVERALL	LAYER THICKNESS				I/O PITCH	PACKAGE TYPE	KYOCERA ALUMINA CODE	CONNECTION		DRAWING No.	TOOL
			1ST	2ND	3RD	TOTAL				SEAL RING	DIE ATTACH		
32	5.50 SQ.	8.00 SQ.	0.40	0.40	0.20	1.00	0.70	LCC	A440	28	N	KD-DB2528	SOFT
32	5.70 SQ.	8.00 SQ.	0.40	0.40	0.20	1.00	0.70	LCC	A440	N	N	KD-DB0G21	SOFT
32	6.73 SQ.	10.668 SQ.	0.57	0.57	0.51	1.65	1.016	LCC	A440	N	N	KD-DA7863	HARD
32	6.73 SQ.	10.668 SQ.	0.57	0.57	0.51	1.65	1.016	LCC	A440	N	0	KD-DB3693	HARD
40	7.27 SQ.	10.16 SQ.	0.40	0.80	0.40	1.60	0.85	LCC	A440	N	N	KD-DB3K70	SOFT
48	7.50 SQ.	10.00 SQ.	0.40	0.40	0.20	1.00	0.70	LCC	A440	N	N	KD-DA6K98	HARD
48	7.50 SQ.	10.00 SQ.	0.40	0.40	0.50	1.30	0.70	LCC	A440	N	18	KD-DB2B73	SOFT
48	7.50 SQ.	10.00 SQ.	0.40	0.40	0.20	1.00	0.70	LCC	A440	42	N	KD-DB2023	SOFT
48	7.50 SQ.	10.00 SQ.	0.40	0.40	0.20	1.00	0.70	LCC	A440	N	N	KD-DB1265 (DAISY)	SOFT
48	7.50 SQ.	11.00 SQ.	0.50	0.50	0.50	1.50	0.80	LCC	A440	N	N	KD-DB0A91	SOFT
48	7.50 SQ.	11.00 SQ.	0.50	0.50	0.50	1.50	0.80	LCC	A440	42	18	KD-DB0N59	HARD
48	7.70 SQ.	10.00 SQ.	0.40	0.40	0.20	1.00	0.70	LCC	A440	N	N	KD-DB0G13	HARD
48	8.00SQ	11.00SQ	0.50	0.50	0.50	1.50	0.80	LCC	A440	N	N	KD-DB0H03	HARD
48	8.50 SQ. SEAL CAVITY	10.00 SQ.	0.70 (1ST:0.35 + 2ND:0.35)		0.30	1.00	0.70	LCC	A440	N	N	KD-DB0457 *NO BONDING SHELF	HARD
48	10.617 SQ.	14.224 SQ.	0.57	0.57	0.51	1.65	1.016	LCC	A440	N	N	KD-DA7069	HARD
48	10.617 SQ.	14.224 SQ.	0.50	0.50	0.50	1.50	1.016	LCC	A440	42	18	KD-DA9L09-B	SOFT
48	10.617 SQ.	14.224 SQ.	0.50	0.50	0.50	1.50	1.016	LCC	A440	42	18	KD-DB1M51-B	SOFT

#=Connected pad number  
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R0189F

UNIT : mm

I/O COUNT	DIE CAV	OVERALL	LAYER THICKNESS				I/O PITCH	PACKAGE TYPE	KYOCERA ALUMINA CODE	CONNECTION		DRAWING No.	TOOL
			1ST	2ND	3RD	TOTAL				SEAL RING	DIE ATTACH		
52	8.00SQ	11.00SQ	0.40	0.30	0.30	1.00	0.70	LCC	A440	N	N	KD-DB0H05	SOFT
52	9.00SQ	11.00SQ	0.40	0.30	0.30	1.00	0.70	LCC	A440	N	N	KD-DB0D16	SOFT
56	9.00SQ	12.00SQ	0.40	0.30	0.30	1.00	0.70	LCC	A440	N	N	KD-DB0H71	SOFT
64	10.50 SQ.	13.00 SQ.	0.40	0.40	0.20	1.00	0.70	LCC	A440	N	N	KD-DA6L79	HARD
64	10.50 SQ.	13.00 SQ.	0.40	0.40	0.50	1.30	0.70	LCC	A440	N	24	KD-DB3666	SOFT
64	10.70 SQ.	13.00 SQ.	0.40	0.40	0.20	1.00	0.70	LCC	A440	N	N	KD-DB0G16	SOFT
64	13.40 SQ	18.00 SQ	0.50	0.50	0.50	1.50	1.00	LCC	A440	N	N	KD-DB1270 (DAISY)	SOFT
64	13.40 SQ	18.00 SQ	0.50	0.50	0.50	1.50	1.00	LCC	A440	N	N	KD-DB6778	SOFT
64	13.40 SQ	18.00 SQ	0.50	0.50	0.50	1.50	1.00	LCC	A440	56	N	KD-DB5M91	SOFT
84	17.78 SQ.	29.21 SQ.	0.508	0.508	1.016	2.032	1.27	LCC	A440	N	0	KD-DB0K65	SOFT
84	22.00 SQ.	29.21 SQ.	0.508	0.508	1.016	2.032	1.27	LCC	A440	N	1	KD-DB6512	SOFT
96	9.00SQ	11.00SQ	0.40	0.30	0.30	1.00	1.00	Land Grid Array	A440	N	N	KD-DB0R81	HARD
96	9.00SQ	11.00SQ	0.40	0.30	0.30	1.00	1.00	Land Grid Array	A440	D2	N	KD-DB2144	SOFT
100	9.00SQ	11.00SQ	0.40	0.30	0.30	1.00	1.00	Land Grid Array	A440	N	N	KD-DB0N53	HARD